DCN No. 1	2017122222			DOW			L-L- 2 2:	017	
PCN Number:	20171002000			PCN Date: October 3, 2017					
Title: Datasheet for									
Customer Contact:	PCN Manager			Dept: Quality Services				ces	
Change Type:									
Assembly Site		Design				Wafer	r Bump Sit	:e	
Assembly Process		Data She	et				r Bump Ma		
Assembly Materials		Part num	ber chang	e			r Bump Pro	ocess	
Mechanical Specific		Test Site				Wafer	r Fab Site		
Packing/Shipping/L	_abeling	Test Proc	ess		Щ		r Fab Mate		
						Wafer	r Fab Proce	ess	
Notification Details									
Description of Change:									
Texas Instruments Incorporated is announcing an information only notification etc.									
The product datasheet(s) is being updated as summarized below.									
The following change history provides further details.									
Br									
TEXAS INSTRUMENTS	TEXAS LIMH12							LMH1297	
INSTRUMENTS				SNLS5	45B –	MARCH 20	17-REVISED SE	EPTEMBER 2017	
								111111	
Changes from Revision A (July 2017) to Revision	on B						Page	
Changed NTps _{max} test condition max from 6 GHz to 50 MHz and < 20 mVp-p NOM to < 10 mVp-p						7			
Changed t _{R.F.SDI} minimum SD rise/fall time from 390 ps to 400 ps due to incorrect default settings									
Changed typical t _R /t _F of OUT0 from 35 ps to 45 ps									
Added PRBS10 pattern to clarify AJ _{CD MODE} and TMJ _{CD MODE} Test Condition									
Added SMBUS SCL min frequency per SMBus 2.0 specifications									
Added Figure 1 to clarify definition of SMBus Timing Parameters in Recommended SMBus Interface Timing									
Specifications									
Added typical characteric curves for OUT0 VOD and de-emphasis vs. LMH1297 register settings						16			
Added default internal pullup and pulldown settings for 2-level strap pins in Figure 20							31		
Added clarification in Table 13 regarding reclocker behavior when used with non-SDI data rates									
 Changed Step 6 description 				A STATE OF THE PARTY OF THE PAR					
between EQ Mode and Cl								and the second s	
Added mechanical, thermal pad, and land pattern drawings to the Package Option Addendum									
The datasheet number v	will be changing								
Device Family	Change From:				Change T	· · · ·			
LMH1297		SNLS545A						SNLS545B	
LITHITZ3/ SINLSJ4JA SINLSJ4JB									
The datasheet is conside	ered "custom". f	or that re	ason: the	docum	ent	is not a	available o	n the TI	
website. Please contact									
		C ,		- (-)		, .			
Reason for Change:									
To more accurately refle	ect device chara	cteristics							
,			uality or	Daliak	:::4.	. (noci	itivo / no	antivo).	
Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):									
No anticipated impact. This is a specification change announcement only. There are no changes to the actual device.									
to the actual device.									
Changes to product identification resulting from this PCN:									
None.									
Product Affected:									
LMH1297RTVR	LMH1297RTV	_	<u> </u>						

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
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